

H1
NY PMS 440 0025 PH

H2
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H3
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H4
NY PMS 440 0025 PH

FID1 FID2 FID3 FID4 FID5 FID6

PCB
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Texas Instruments

PCB
LOGO
ESD Susceptible

PCB Part Number: 551007837-001 REV B

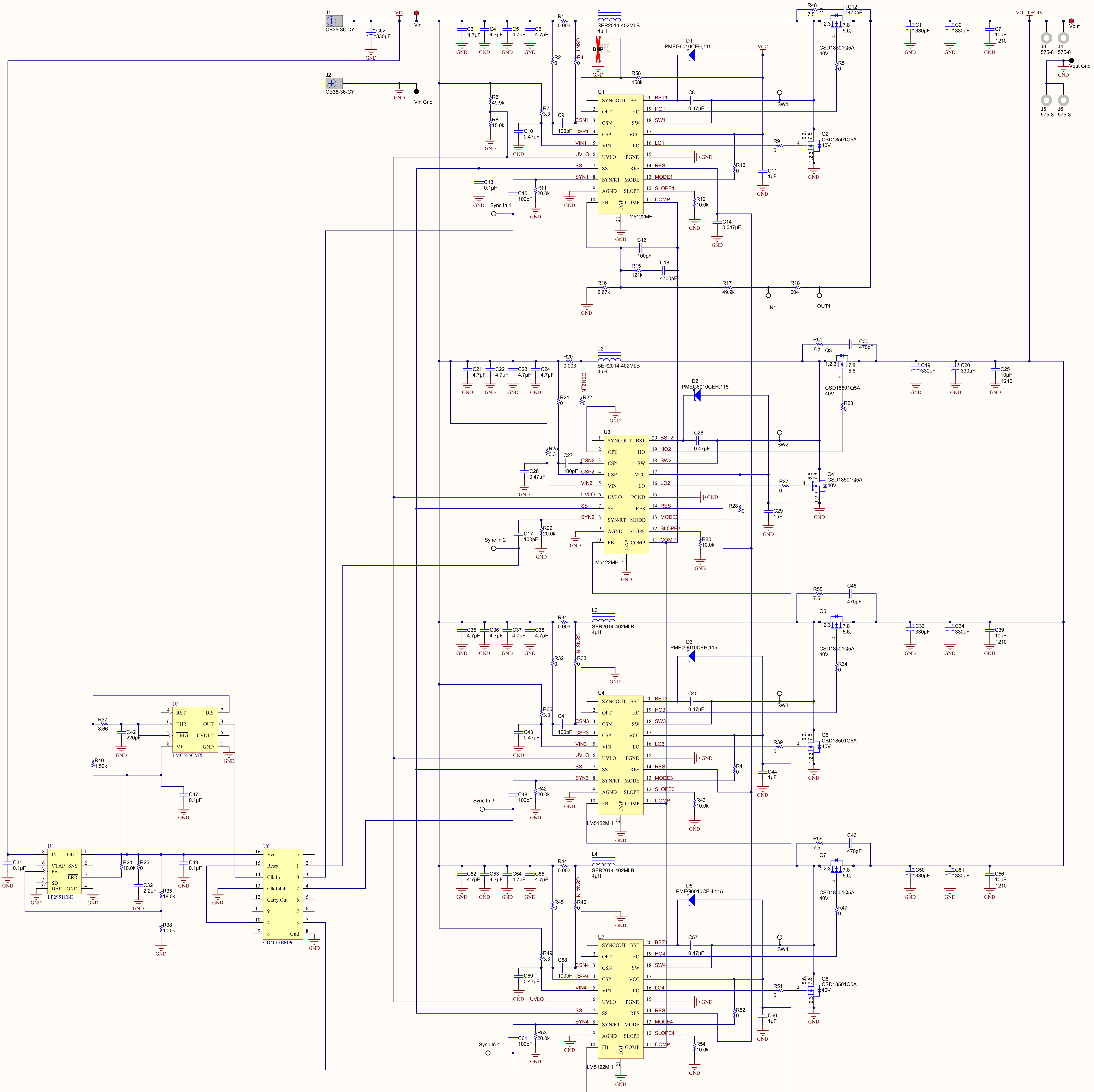
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Designed for: [Texas Instruments Corporation](#) Date: 5/16/2012
Project: [PMP7837 REV B](#)
Sheet Title: [ChangeMe](#) Sheet: 1 of 1
Size: B Schematic: [870007837](#) Rev: X1
Assembly Variant: [-200 REV B](#)
File: [Hardware_ANSI-B_SchDoc](#)
Contact: <http://www.national.com/support>



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Title		
Size	Number	Revision
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File: C:\Alum 10 C Drive\PMPT837 Rev 9\Shuman\BschDoc		

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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